EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	350	425/128.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2009/01/08 11:52
L4	17327	257/787.ccls. 257/ e21.502.ccls. 257/ e21.504.ccls. 257/ e21.705.ccls. 257/ e23.116.ccls. 257/ e23.125.ccls. 438/108. ccls. 438/124.ccls. 438/126.ccls. 438/127.ccls. 156/500.ccls. 425/117.ccls. 425/125.ccls. 425/128.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2009/01/08 11:54
L5	372	L4 and ((encapsulat $6 mold$6 packag$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity feed$6 assembl$6) same (edge project$6) same (movable displac $6 support receiv$6 force part))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2009/01/08 11:54
L6	408	(encapsulat$6 mold $6 packag$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity space open$6) same (feed $6 assembl$6) same (edge project$6)	US-PGPUB; USPAT	OR	ON	2009/01/08 12:07

		same (mov$6 displac $6 adjust$6) same (support receiv$6 force part)				
L7	226	(encapsulat$6 mold $6 packag$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open$6) and (feed$6 assembl$6) and (edge project$6) and (mov$6 displac$6 adjust$6) and (support receiv$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/08 12:13

1/8/09 12:19:07 PM
C:\Documents and Settings\ssmoot\My Documents\EAST\Workspaces\10541715.wsp